

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPIC
 IMM. TIN/SILVER OR EQUIV OTHER _____

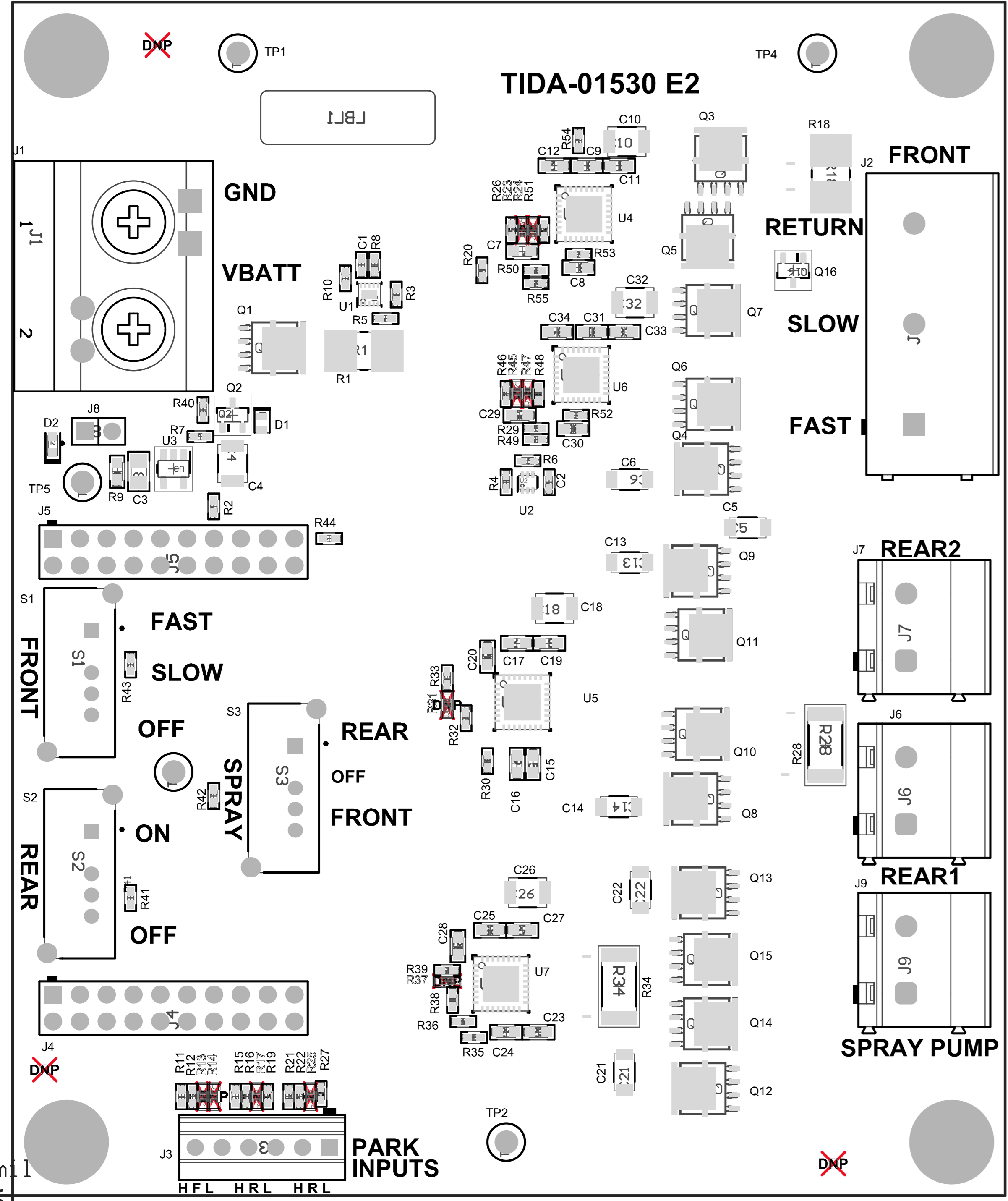
ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

ZZ1
 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.



J4 and J5 are mounted on the BOTTOM of the board.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

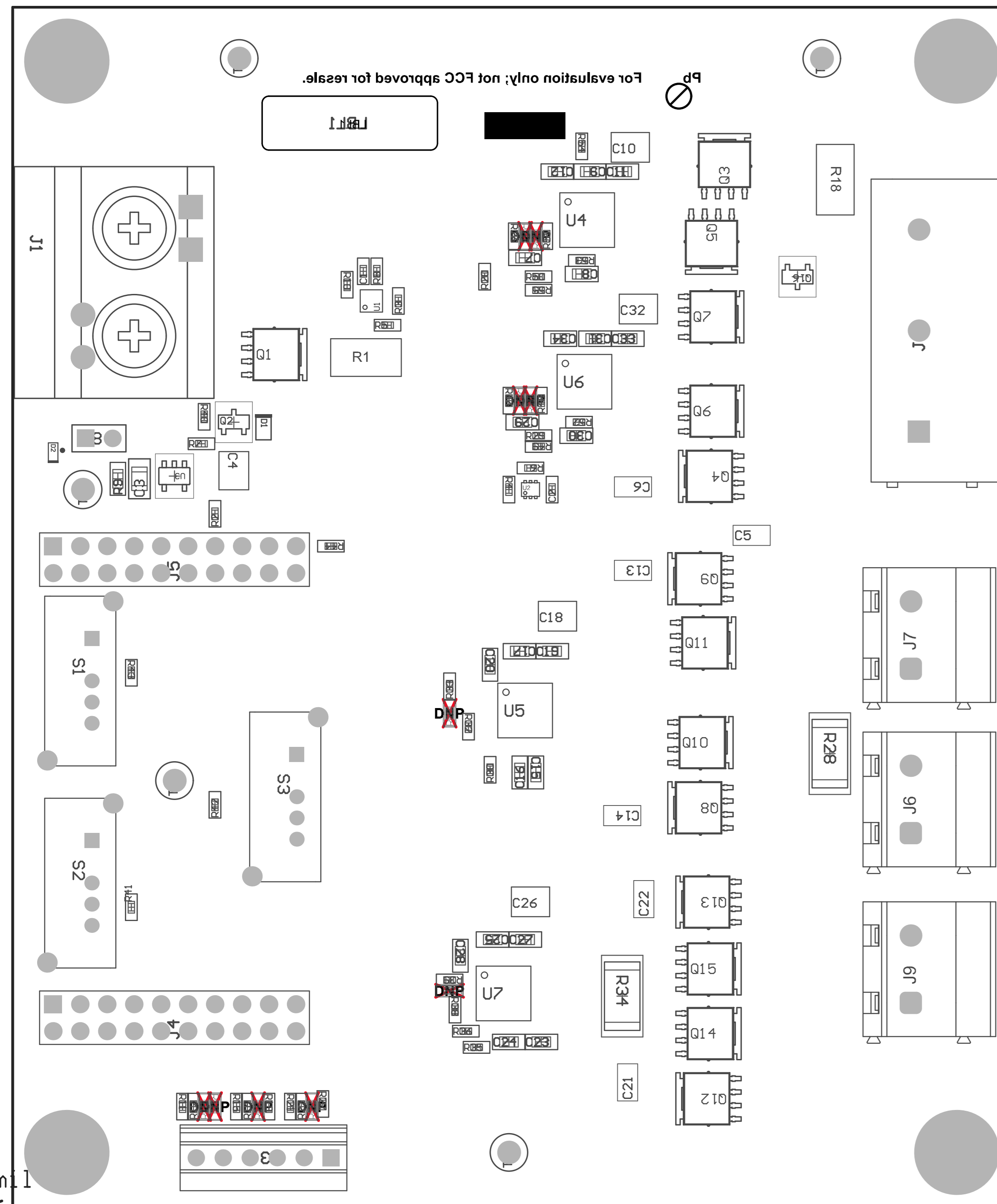
ADD TO BOM	REV	DATE	BY	DESCRIPTION
1	0	01/16/2018	AK	INITIAL RELEASE
2	1	02/08/2018	AK	DESIGN CHANGES
3	2	02/08/2018	AK	DESIGN CHANGES
4	3	02/08/2018	AK	DESIGN CHANGES
5	4	02/08/2018	AK	DESIGN CHANGES
6	5	02/08/2018	AK	DESIGN CHANGES
7	6	02/08/2018	AK	DESIGN CHANGES

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ENGINEER:	LAYOUT BY:
C.Kinnaird	C.Kinnaird
SCALE: 1.00	ALTIUM DESIGNER VERSION:
	17.1.5.472

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 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER



PROJECT TITLE: Automotive Windshield Wiper Drive

DESIGNED FOR: Public Release

FILE NAME: TIDA01530E3.PcbDoc

ENGINEER: C.Kinnaird LAYOUT BY: C.Kinnaird

SCALE: 1.00 ALTIUM DESIGNER VERSION: 17.1.5.472

COMPONENTS MARKED 'DNP' SHOULD NOT BE CAPTURED TO THE BOARD. COMPONENTS MARKED 'DNP' SHOULD NOT BE CAPTURED TO THE BOARD.
 ASSEMBLY VARIANT: 001

ADD TO BOARD	REMOVE FROM BOARD	BOARD #	TID #	DATE	DESIGNER	DESCRIPTION
		01530E3	01530E3	01530E3	01530E3	01530E3

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